

DOUBLE SIDED LAPPING/POLISHING MACHINE

双面研磨/抛光机 YJ-9.6B10L/PE&YJ-9B5L/PE

本机器主要适用于硅片、石英晶片、光学晶体、玻璃、宝石、铌酸锂、砷化镓、陶瓷片等薄脆金属或非金属的研磨或抛光。

The machine is suitable for double side lapping and polishing of thin and fragile metal or non-metal parts such as silicon wafer, crystal quartz, optical crystal, glass, jewelry, lithium niobium acid, gallium arsenide, and ceramic wafer, etc.



手机盖板



玻璃屏

设备特点

- 机器采用三电机驱动，工件上下表面同时均匀研磨/抛光，生产效率高；
- 机器采用内齿圈升降，内齿圈升降采用点动控制方式操作，使操作者能自由控制齿圈升降高度；
- 下盘不抬升，设置了调节水平的三点支撑结构，可对下盘的偏斜进行微调，以提高机器精度；
- 电机采用变频调速器控制，能在有效设置范围内以任意速度工作；
- 气动系统采用优质气控元件，上盘、齿圈升降平稳无爬行现象，上盘下降过程中，设置了快降和缓降；
- 太阳轮、齿圈皆可以单独调速，能灵活调整工艺参数，工艺适应性强。

MAIN TECHNICAL FEATURES

- Equipped with three motors. Both sides of work pieces can be evenly lapped.
- Ring gear position is adjustable by jog operation.
- Lower plate can be adjusted by the three-point supporting structure.
- Variable frequency speed governor realizes soft start, and soft stop. Machine can work under any speed which is within setting range.
- High quality pneumatic components ensures stable up and down movement.
- Sun gear and ring gear speed can be adjusted separately.

主要技术参数 MAIN TECHNICAL SPECIFICATIONS

项目/Items	YJ-9B5L/PE	YJ-9.6B10L/PE
上/下盘尺寸(Upper/Lower plate size)	φ638×φ222×40(mm)	φ622×φ386×40(mm)
工件厚度(Thickness of workpiece)	最大Max:20(mm) 最小Min:0.15(mm)	最大Max:20(mm)
工件直径(Dimensions of workpiece)	最大Max:φ180(mm)	最大Max:φ100(mm)
下盘转速(Lower plate rotational speed)	0-50(r/min)	0-50(r/min)
游星轮数量(Number of Planet gears)	5	10
内齿圈抬升行程 (Lifting stroke of inner gear ring)	0-25(mm)	0-25(mm)
主电机(Main motor)	3相 3(kw)可增至5.5(kw) 1450 (r/min)	3相 3(kw) 1450 (r/min)
砂泵电机(Slurry pump motor)	120(W)	120(W)
气源压力(Air pressure)	0.5-0.6(Mpa)	0.5-0.6(Mpa)
工作压力(Working pressure)	0.45-0.6(Mpa)	0.45-0.6(Mpa)
机器外形尺寸(Size L×W×H)	1400×970×2340(mm)	1460×1178×2490(mm)
机器重量(Weight)	~ 1900(Kg)	~ 1900(Kg)